

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A card comprising:
 - a display device comprising a first semiconductor element comprising a first polycrystalline semiconductor film;
 - a first thin film integrated circuit comprising a second semiconductor element comprising a second polycrystalline semiconductor film;
 - a first substrate; and
 - a second substrate,
wherein the display device is electrically connected to the first thin film integrated circuit,
 - wherein the thin film integrated circuit and the display device are covered and sealed with a resin between the first substrate and the second substrate of the card, and
 - wherein the first substrate and the second substrate comprise a plastic material.
2. (Original) A card according to claim 1, wherein the card has a thickness from 0.05 mm through 1.5 mm.
3. (Previously Presented) A card according to claim 1, wherein the display device is a passive matrix type display device.
4. (Original) A card according to claim 1, wherein the display device is an active matrix type.

5. (Previously Presented) A card according to claim 1, further comprising:
a second thin film integrated circuit,
wherein the first and second thin film integrated circuits are laminated.

6.-8. (Canceled)

9. (Previously Presented) A card according to claim 1, wherein the display device is a liquid crystal display device.

10. (Canceled)

11. (Previously Presented) A card according to claim 1, wherein the display device is a light emitting device.

12. (Canceled)

13. (Previously Presented) A card according to claim 1, wherein the card is an ID card.

14. (Canceled)

15. (Previously Presented) A card according to claim 1, wherein the card is a semi-hard card.

16. (Canceled)

17. (Previously Presented) A card according to claim 1, wherein the card is an IC card.

18.-19. (Canceled)

20. (New) A card comprising:

a first substrate comprising a plastic material;
a display device comprising a first semiconductor element comprising a first polycrystalline semiconductor film over the first substrate;
a thin film integrated circuit comprising a second semiconductor element comprising a second polycrystalline semiconductor film over the first substrate;
a resin over the display device and the thin film integrated circuit; and
a second substrate comprising a plastic material over the resin.